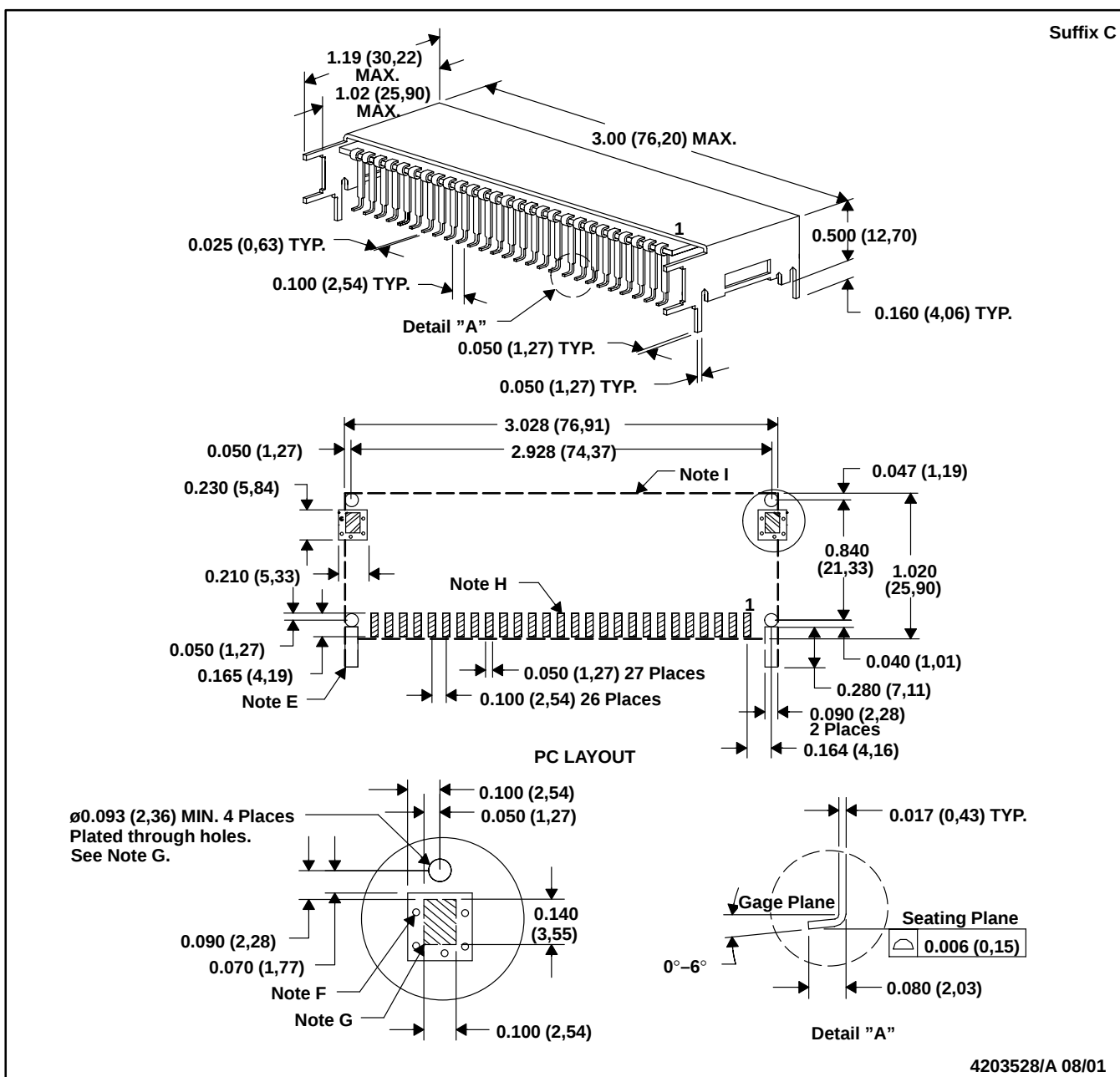


ENG (R-MSIP-G27)

METAL SINGLE-IN-LINE MODULE



- NOTES:
- All linear dimensions are in inches (mm).
 - This drawing is subject to change without notice.
 - 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 - 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 - Recommended mechanical keep out area.
 - Vias are recommended to improve copper adhesion.
 - Solder mask openings to copper island for solder joints to mechanical pins. Electrically connect case to power ground plane.
 - Power pin connections should utilize two or more vias per input, ground and output pin.
 - Case outline reference.

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